

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau

(43) International Publication Date
26 December 2024 (26.12.2024)



(10) International Publication Number
WO 2024/261390 A1

(51) International Patent Classification:

C23C 16/455 (2006.01) H01L 21/67 (2006.01)
C23C 16/458 (2006.01) H01L 21/677 (2006.01)
C23C 16/46 (2006.01) H01L 21/687 (2006.01)
C23C 16/54 (2006.01)

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(21) International Application Number:

PCT/FI2024/050311

(22) International Filing Date:

13 June 2024 (13.06.2024)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

20235717 21 June 2023 (21.06.2023) FI

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(81) Designated States (unless otherwise indicated, for every
kind of national protection available): AE, AG, AL, AM,
AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ,
CA, CH, CL, CN, CO, CR, CU, CV, CZ, DE, DJ, DK, DM,
DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT,
HN, HR, HU, ID, IL, IN, IQ, IR, IS, IT, JM, JO, JP, KE, KG,
KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY,
MA, MD, MG, MK, MN, MU, MW, MX, MY, MZ, NA,
NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO,
RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH,
TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS,
ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every
kind of regional protection available): ARIPO (BW, CV,
GH, GM, KE, LR, LS, MW, MZ, NA, RW, SC, SD, SL, ST,
SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ,
RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ,

(54) Title: A THIN-FILM DEPOSITION APPARATUS CLUSTER

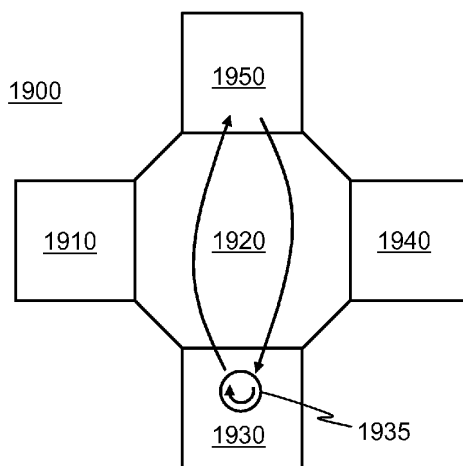


Fig. 19

(57) Abstract: A substrate processing system (1900) comprising, a reception module (1910) configured to load and unload substrates (130) to and from the substrate processing system (1900), and a heating module (1930) configured to heat substrates (130), and at least one processing module (1950) configured to process the substrates (130) with sequential self-limiting surface reactions, the at least one processing module (1910) comprising a laminar flow reaction chamber (120) and a substrate lifting system (500) configured to transfer substrates (130), in a direction perpendicular to surfaces thereof, between a loading position and a processing position, and a transfer unit (1910) comprising a robotic system configured to transfer the substrates (130) between said reception module, said heating module, and said at least one processing module.

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DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT,
LU, LV, MC, ME, MK, MT, NL, NO, PL, PT, RO, RS, SE,
SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN,
GQ, GW, KM, ML, MR, NE, SN, TD, TG).

Declarations under Rule 4.17:

— *of inventorship (Rule 4.17(iv))*

Published:

— *with international search report (Art. 21(3))*
— *in black and white; the international application as filed
contained color or greyscale and is available for download
from PATENTSCOPE*